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(12) **United States Design Patent**
Lee

(10) **Patent No.:** **US D480,964 S**

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(54) **BLISTER PACK**

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(**) **Term:** **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (7) Cl.** **09-03**

(52) **U.S. Cl.** **D9/415**

(58) **Field of Search** D9/414, 415, 418,
D9/337, 457; 206/461-471, 806, 495, 769-776,
701-705

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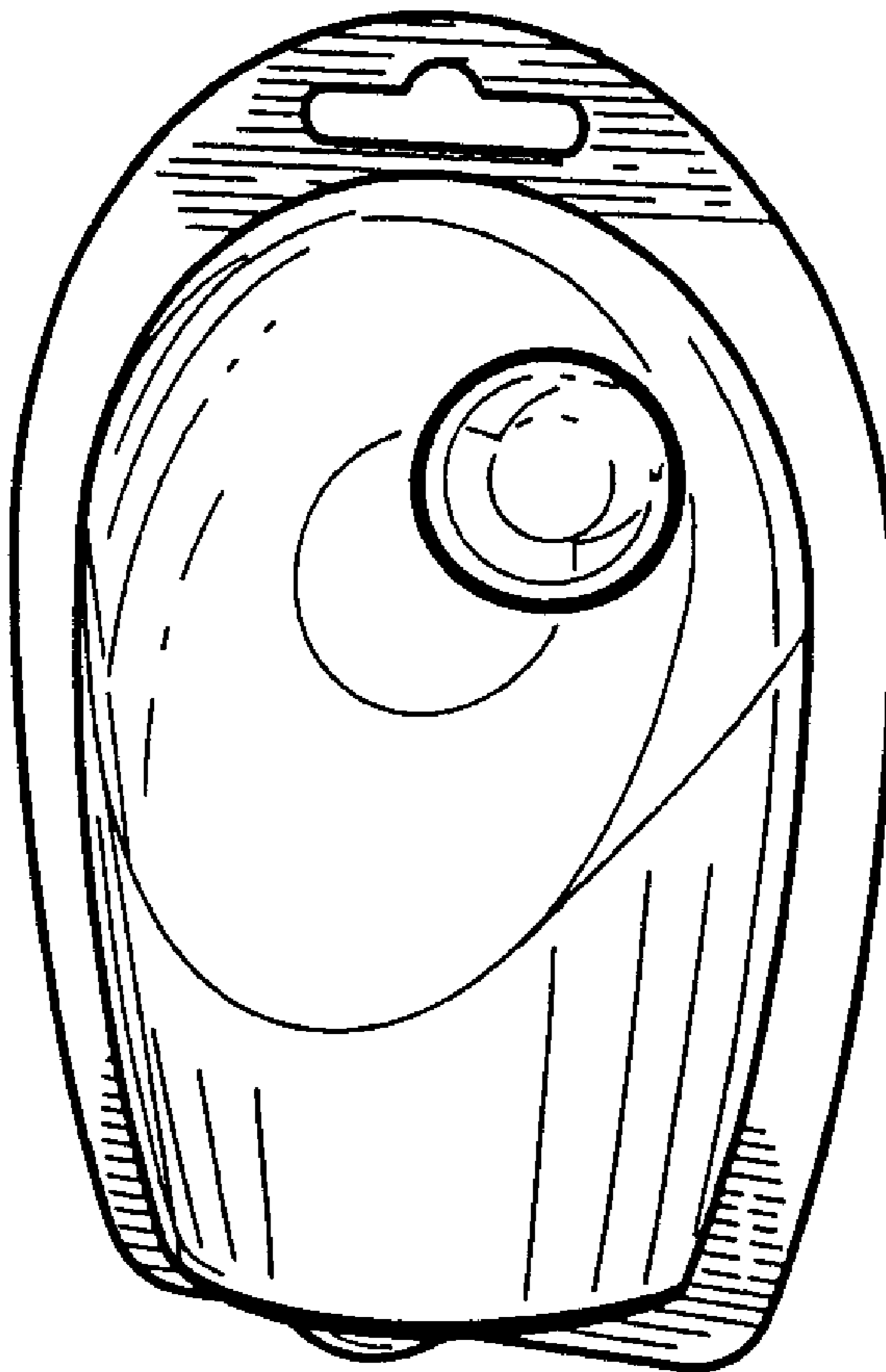
(57) **CLAIM**

The ornamental design for a blister pack, as shown.

DESCRIPTION

FIG. 1 is a perspective view showing my design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 2 Drawing Sheets



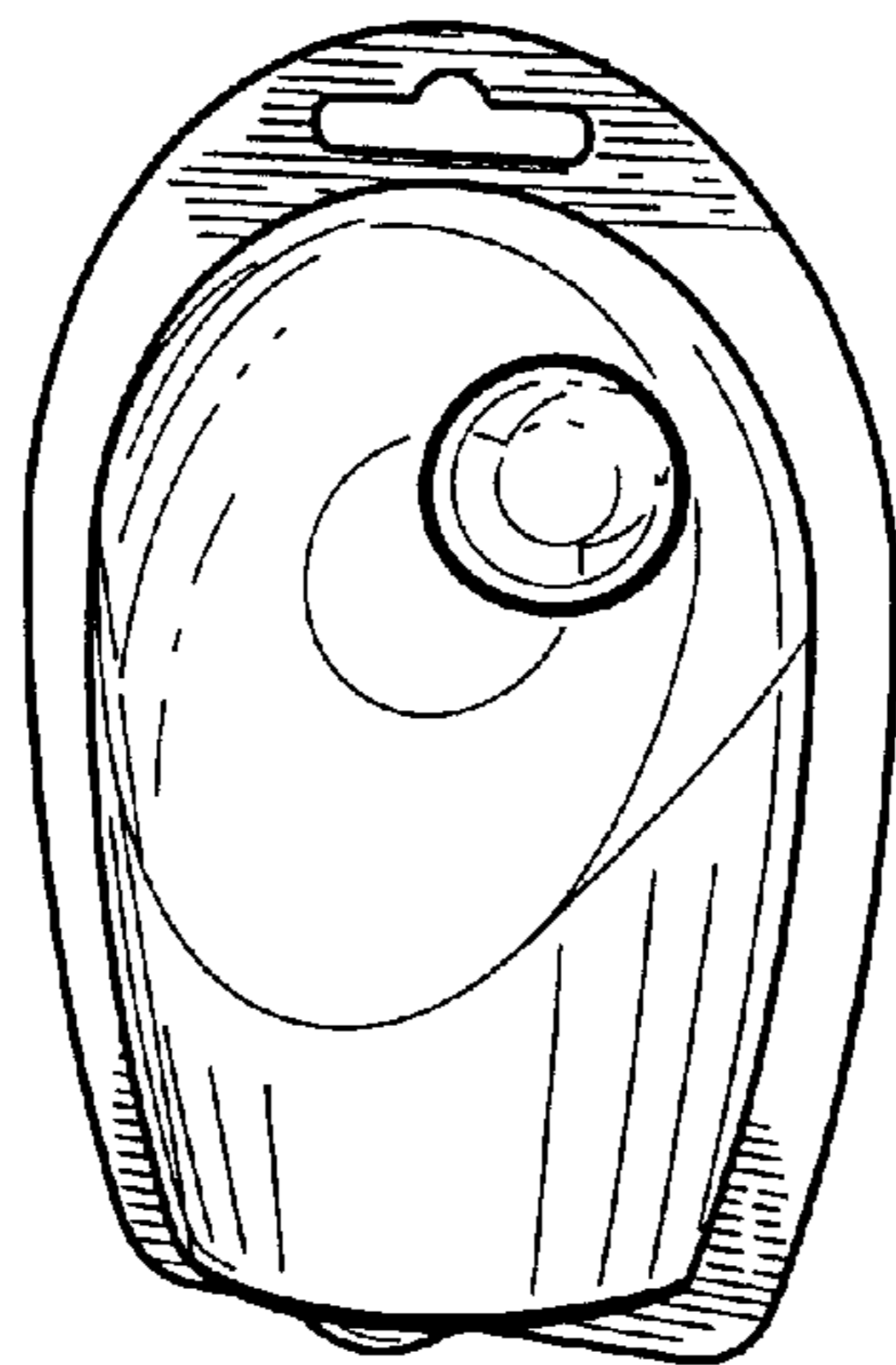


FIG. 1

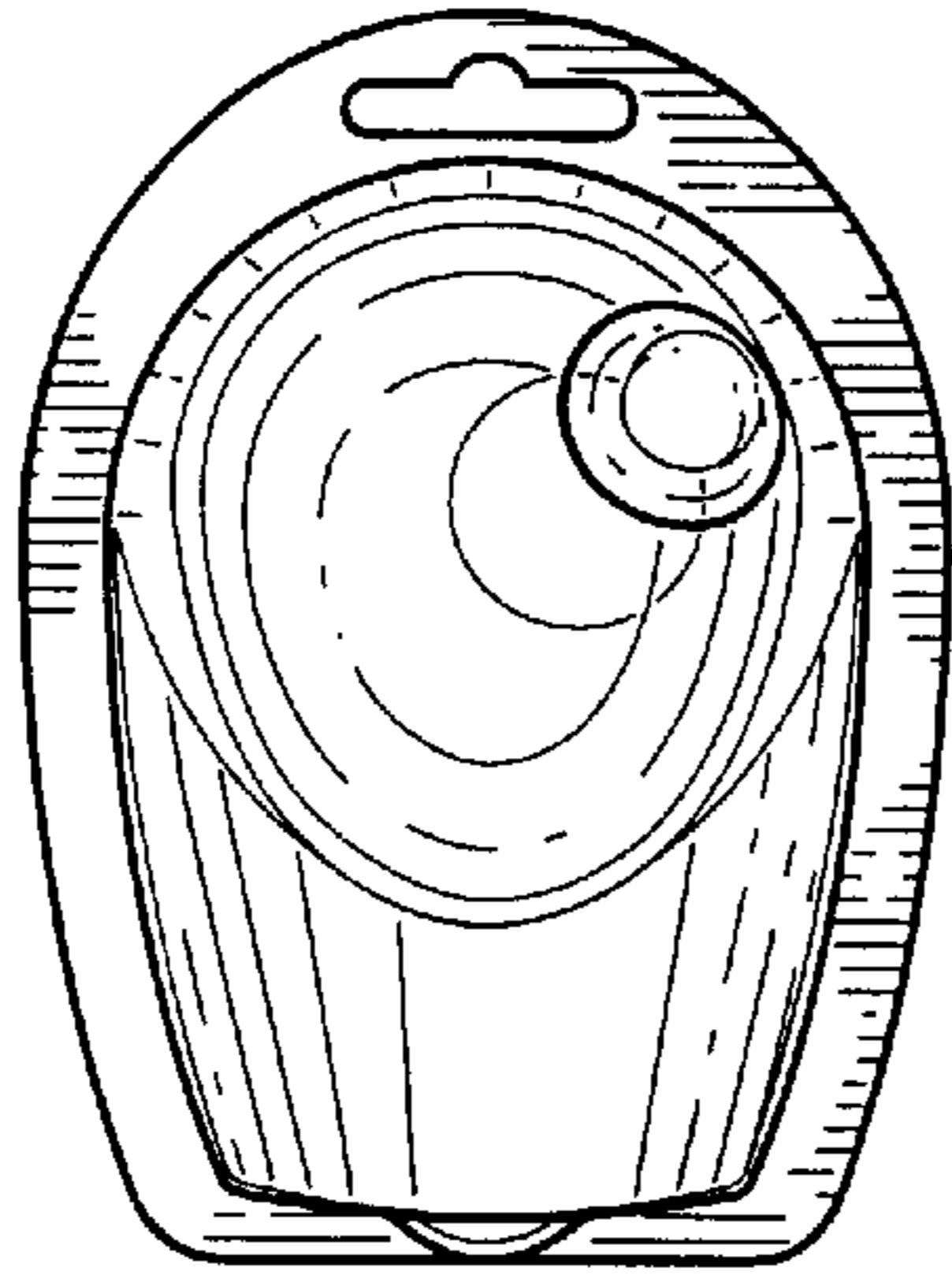


FIG. 2

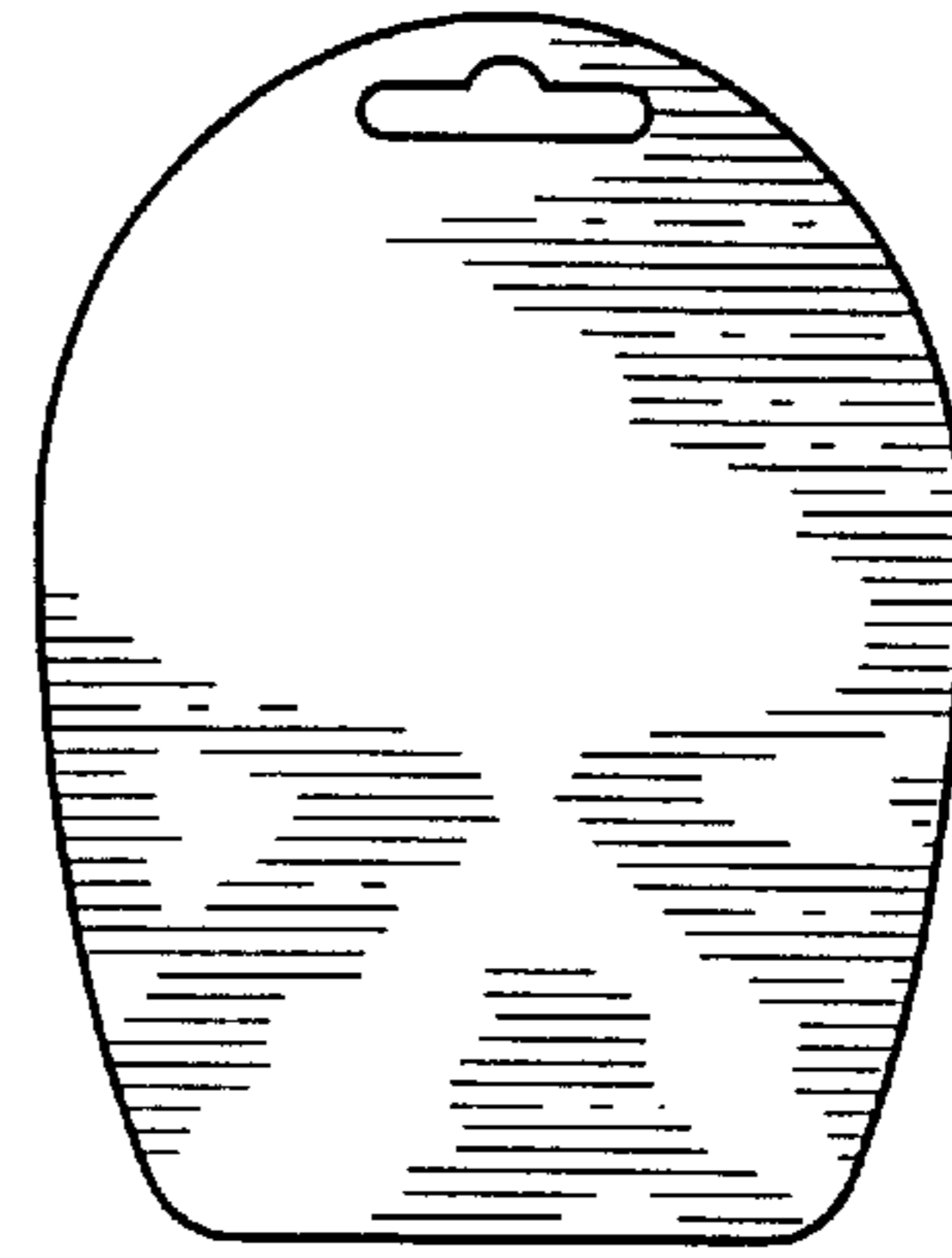


FIG. 3



FIG. 4



FIG. 5



FIG. 6



FIG. 7